Infineon Technologies - MB90F351ESPMC-GS-SPE1 Datasheet

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What is "Embedded - Microcontrollers"?

"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Obsolete
Core Processor	F²MC-16LX
Core Size	16-Bit
Speed	24MHz
Connectivity	CANbus, EBI/EMI, I²C, LINbus, UART/USART
Peripherals	DMA, LVD, POR, WDT
Number of I/O	51
Program Memory Size	64KB (64K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	4K x 8
Voltage - Supply (Vcc/Vdd)	3.5V ~ 5.5V
Data Converters	A/D 15x8/10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 125°C (TA)
Mounting Type	Surface Mount
Package / Case	64-LQFP
Supplier Device Package	64-LQFP (12x12)
Purchase URL	https://www.e-xfl.com/product-detail/infineon-technologies/mb90f351espmc-gs-spe1

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Part Number / Parameter	MB90351E MB90352E	MB90351TE MB90352TE	MB90351ES MB90352ES	MB90351TES MB90352TES	MB90V340E-101	MB90V340E-102
16-bit output compare	4 channels				8 channels	
	Signals an interrupt when 16-bit free-run Timer matches output compare registers. A pair of compare registers can be used to generate an output signal.					
16-bit input capture	6 channels				8 channels	
	Retains 16-bit free-run timer value by (rising edge, falling edge, or the both edges), signals an interrupt.					
8/16-bit programmable pulse generator	6 channels (16-bit)/10 channels (8-bit) 8-bit reload counters × 12 8-bit reload registers for L pulse width×12 8-bit reload registers for H pulse width×12				8 channels (16-bit)/ 16 channels (8-bit) 8-bit reload counters × 16 8-bit reload registers for L pulse width × 16 8-bit reload registers for H pulse width × 16	
	Supports 8-bit and 16-bit operation modes. A pair of 8-bit reload counters can be configured as one 16-bit reload counter or as 8-bit prescaler + 8-bit reload counter. Operation clock frequency : fsys, fsys/2^1, fsys/2^2, fsys/2^3, fsys/2^4 or 128 μs@fosc = 4 MHz (fsys = Machine clock frequency, fosc = Oscillation clock frequency)					
CAN interface	1 channel				3 channels	
	Compliant with CAN standard Version 2.0 Part A and Part B. Automatic re-transmission in case of error Automatic transmission responding to Remote Frame 16 prioritized message buffers for data and ID Supports multiple messages. Flexible configuration of acceptance filtering : Full bit compare/Full bit mask/Two partial bit masks Supports up to 1 Mbps.					
External interrupt	8 channels				16 channels	
	Can be used rising edge, falling edge, starting up by “H”/“L” level input, external interrupt, extended intelligent I/O services (EI^{2}OS) and DMA.					
D/A converter	—				2 channels	
I/O ports	Virtually all external pins can be used as general purpose I/O port. All push-pull outputs Bit-wise settable as input/output or peripheral signal Settable as CMOS schmitt trigger/ automotive inputs TTL input level settable for external bus (only for external bus pin)					
Flash memory	—					
Corresponding evaluation name	MB90V340E-102		MB90V340E-101		—	

* : It is setting of Jumper switch (TOOL VCC) when Emulator (MB2147-01) is used.
Please refer to the Emulator hardware manual about details.

■ MASK ROM products/Evaluation products

Parameter \ Part Number	MB90356E MB90357E	MB90356TE MB90357TE	MB90356ES MB90357ES	MB90356TES MB90357TES	MB90V340E-103	MB90V340E-104
CPU	F^2MC-16LX CPU					
System clock	On-chip PLL clock multiplier (×1, ×2, ×3, ×4, ×6, 1/2 when PLL stops) Minimum instruction execution time : 42 ns (oscillation clock 4 MHz, PLL × 6)					
ROM	MASK ROM 64 Kbytes :MB90356E(S), MB90356TE(S) 128 Kbytes :MB90357E(S), MB90357TE(S)				External	
RAM	4 Kbytes				30 Kbytes	
Emulator-specific power supply*	—				Yes	
Sub clock pin (X0A, X1A)	Yes		No		No	Yes
Clock supervisor	Yes					
Low voltage/CPU operation detection reset	No	Yes	No	Yes	No	
Operating voltage range	3.5 V to 5.5 V : at normal operating (not using A/D converter) 4.0 V to 5.5 V : at using A/D converter 4.5 V to 5.5 V : at using external bus				5 V ± 10%	
Operating temperature range	−40°C to +125°C				—	
Package	LQFP-64				PGA-299	
LIN-UART	2 channels				5 channels	
	Wide range of baud rate settings using a dedicated baud rate generator (reload timer) Special synchronous options for adapting to different synchronous serial protocols LIN functionality working either as master or slave LIN device					
I^2C (400 kbps)	1 channel				2 channels	
A/D converter	15 channels				24 channels	
	10-bit or 8-bit resolution Conversion time : Min 3 μs includes sample time (per one channel)					
16-bit reload timer (4 channels)	Operation clock frequency : fsys/2^1, fsys/2^3, fsys/2^5 (fsys = Machine clock frequency) Supports External Event Count function.					
16-bit free-run timer (2 channels)	Free-run Timer 0 (clock input FRCK0) corresponds to ICU 0/1. Free-run Timer 1 (clock input FRCK1) corresponds to ICU 4/5/6/7, OCU 4/5/6/7.				Free-run Timer 0 corresponds to ICU 0/1/2/3, OCU 0/1/2/3. Free-run Timer 1 corresponds to ICU 4/5/6/7, OCU 4/5/6/7.	
	Signals an interrupt when overflowing. Supports Timer Clear when a match with Output Compare (Channel 0, 4) . Operation clock frequency : fsys, fsys/2^1, fsys/2^2, fsys/2^3, fsys/2^4, fsys/2^5, fsys/2^6, fsys/2^7 (fsys = Machine clock frequency)					

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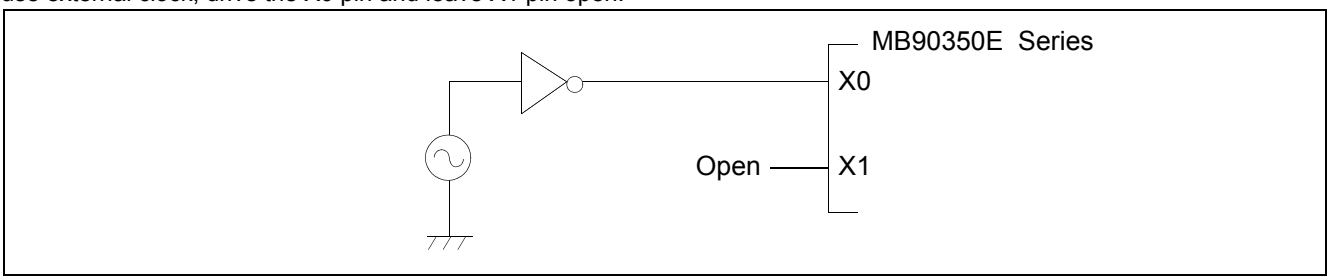
3. Using external clock

To use external clock, drive the X0 pin and leave X1 pin open.



4. Precautions for when not using a sub clock signal

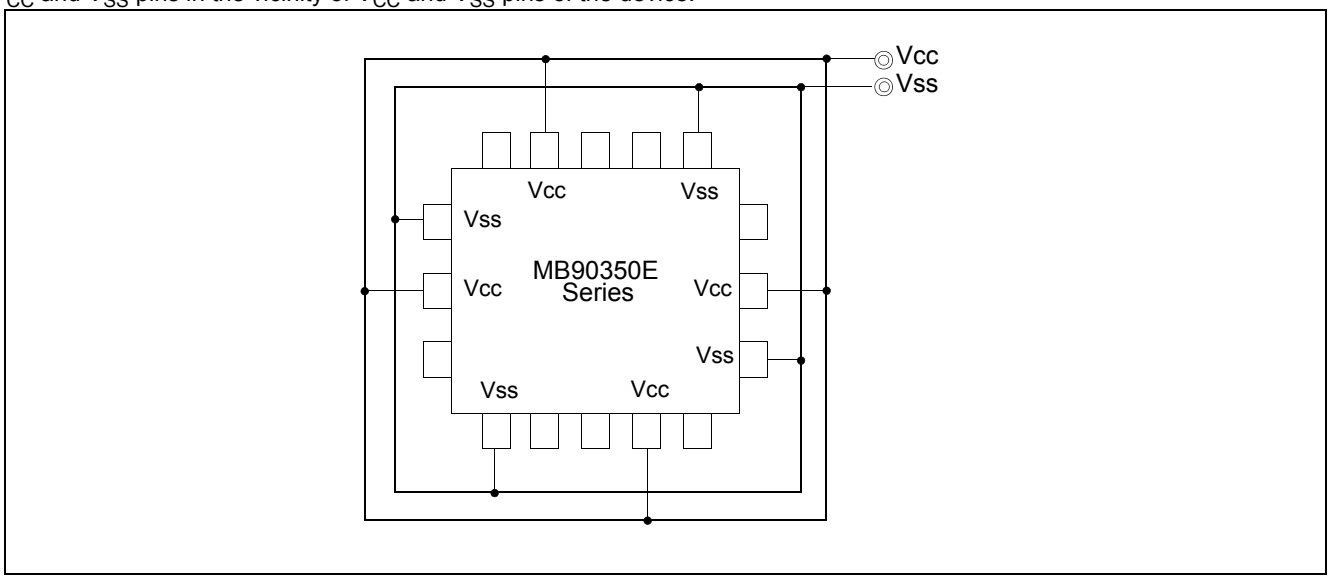
X0A and X1A are oscillation pins for sub clock. If you do not connect pins X0A and X1A to an oscillator, use pull-down handling on the X0A pin, and leave the X1A pin open.

5. Notes on during operation of PLL clock mode

On this microcontroller, if in case the crystal oscillator breaks off or an external reference clock input stops while the PLL clock mode is selected, a self-oscillator circuit contained in the PLL may continue its operation at its self-running frequency. However, Cypress will not guarantee results of operations if such failure occurs.

6. Treatment of Power Supply Pins (V_{CC}/V_{SS})

- If there are multiple V_{CC} and V_{SS} pins, from the point of view of device design, pins to be of the same potential are connected inside of the device to prevent malfunction such as latch-up.
  To reduce unnecessary radiation, prevent malfunctioning of the strobe signal due to the rise of ground level, and observe the standard for total output current, be sure to connect the V_{CC} and V_{SS} pins to the power supply and ground externally.
  Connect V_{CC} and V_{SS} pins to the device from the current supply source at a possibly low impedance.
- As a measure against power supply noise, it is recommended to connect a capacitor of about 0.1 µF as a bypass capacitor between V_{CC} and V_{SS} pins in the vicinity of V_{CC} and V_{SS} pins of the device.



7. Pull-up/down resistors

The MB90350E series does not support internal pull-up/down resistors (Port 0 to Port 3: built-in pull-up resistors). Use external components where needed.

8. Crystal oscillator circuit

Noise around the X0/X1, or X0A/X1A pins may cause this device to operate abnormally. In the interest of stable operation it is strongly recommended that printed circuit artwork places ground bypass capacitors as close as possible to the X0/X1, X0A/X1A and crystal oscillator (or ceramic oscillator) and that oscillator lines do not cross the lines of other circuits.

Please ask each crystal maker to evaluate the oscillational characteristics of the crystal and this device.

9. Turning-on sequence of power supply to A/D converter and analog inputs

Make sure to turn on the A/D converter power supply (AV_{CC}, AVRH) and analog inputs (AN0 to AN14) after turning-on the digital power supply (V_{CC}) .Turn-off the digital power after turning off the A/D converter power
supply and analog inputs. In this case, make sure that the power supply voltage does not exceed the rated voltage of the A/D converter (turning on/of the analog and digital power supplies simultaneously is acceptable).

10. Connection of unused pins of A/D converter if A/D converter is not used

Connect unused pins of A/D converter to $AV_{CC} = V_{CC}$, $AV_{SS} = AVRH = V_{SS}$.

11. Notes on energization

To prevent the internal regulator circuit from malfunctioning, set the voltage rise time during energization at
50 µs or more (0.2 V to 2.7 V) .

12. Stabilization of power supply voltage

A sudden change in the supply voltage may cause the device to malfunction even within the V_{CC} supply voltage operating range. Therefore, the V_{CC} supply voltage should be stabilized. For reference, the supply voltage should be controlled so that V_{CC} ripple variations (peak- to-peak values) at commercial frequencies (50 MHz/
60 MHz) fall below 10% of the standard V_{CC} supply voltage and the coefficient of fluctuation does not exceed 0.1 V/ms at instantaneous power switching.

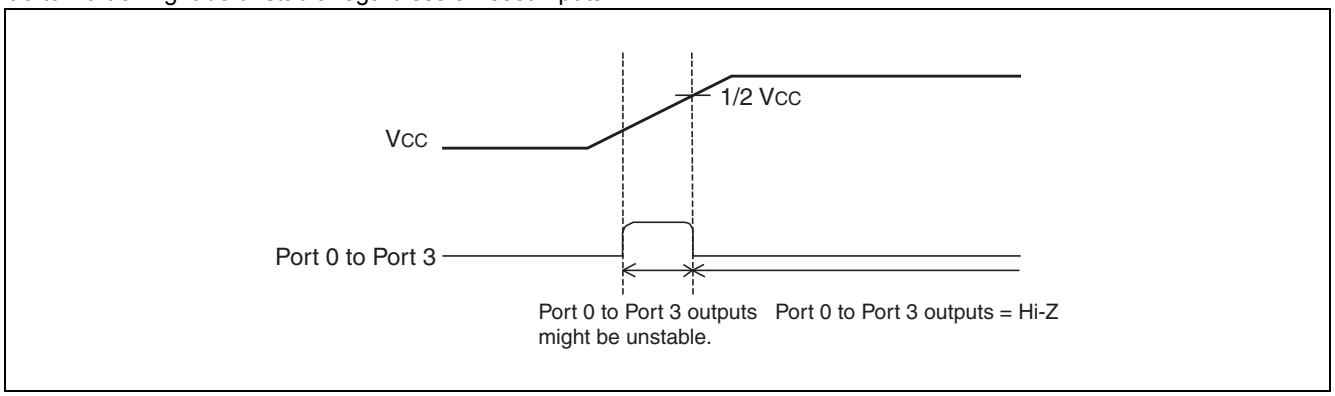
13. Serial Communication

There is a possibility to receive wrong data due to the noise or other causes on the serial communication. Therefore, design a printed circuit board so as to avoid noise.

Retransmit the data if an error occurs because of applying the checksum to the last data in consideration of receiving wrong data due to the noise.

14. Port 0 to port 3 output during power-on (External-bus mode)

As shown below, when power is turned on in external-bus mode, there is a possibility that output signal of Port 0 to Port 3 might be unstable regardless of reset inputs.



15. Setting using CAN function

To use CAN function, please set “1” to DIRECT bit of CAN direct mode register (CDMR).

16. Flash security function

The security byte is located in the area of the Flash memory. If protection code 01_H is written in the security byte, the Flash memory is in the protected state by security.
Therefore please do not write 01_H in this address if you do not use the security function.
Please refer to following table for the address of the security byte.

Product name	Flash memory size	Address for security bit
MB90F352E(S) MB90F352TE(S) MB90F357E(S) MB90F357TE(S)	Embedded 1 Mbit Flash memory	$FE0001_H$

17. Operation with T_A = +105°C or more

If used exceeding $T_A = +105°C$, please contact Cypress sales representatives for reliability limitations.

18. Low voltage/CPU operation reset circuit

The low voltage detection reset circuit is a function that monitors power supply voltage in order to detect when a voltage drops below a given voltage level. When a low voltage condition is detected, an internal reset signal is generated.
The CPU operation detection reset circuit is a 20-bit counter that uses oscillation as a count clock and generates an internal reset signal if not cleared within a given time after startup.

(1) Low voltage detection reset circuit

Detection voltage
4.0 V ± 0.3 V

When a low voltage condition is detected, the low voltage detection flag (LVRC : LVRF) is set to “1” and an internal reset signal is output.
Because the low voltage detection reset circuit continues to operate even in stop mode, detection of a low voltage condition generates an internal reset and releases stop mode.

During an internal RAM write cycle, low voltage reset is generated after the completion of writing. During the output of this internal reset, the reset output from the low voltage detection reset circuit is suppressed.

(2) CPU operation detection reset circuit

The CPU operation detection reset circuit is a counter that prevents program runaway. The counter starts automatically after a power-on reset, and must be continually and regularly cleared within a given time. If the given time interval elapses and the counter has not been cleared, a cause such as infinite program looping is assumed and an internal reset signal is generated. The internal reset generated from the CPU operation detection circuit has a width of 5 machine cycles.

Interval time
$2^{20}/F_C$ (approx. 262 ms*)

* : This value assumes the interval time at an oscillation clock frequency of 4 MHz.
During recovery from standby mode, the detection period is the maximum interval plus 20 μs.

This circuit does not operate in modes where CPU operation is stopped.
The CPU operation detection reset circuit counter is cleared under any of the following conditions.

- ■“0” writing to CL bit of LVRC register
- ■Internal reset
- ■Main oscillation clock stop
- ■Transit to sleep mode
- ■Transit to timebase timer mode and watch mode

19. Internal CR oscillation circuit

Parameter	Symbol	Value			Unit
		Min	Typ	Max	
Oscillation frequency	f_{RC}	50	100	200	kHz
Oscillation stabilization wait time	tstab	—	—	100	μs

10. I/O Map

Address	Register	Abbreviation	Access	Resource name	Initial value
000000_H	Port 0 Data Register	PDR0	R/W	Port 0	$XXXXXXXX_B$
000001_H	Port 1 Data Register	PDR1	R/W	Port 1	$XXXXXXXX_B$
000002_H	Port 2 Data Register	PDR2	R/W	Port 2	$XXXXXXXX_B$
000003_H	Port 3 Data Register	PDR3	R/W	Port 3	$XXXXXXXX_B$
000004_H	Port 4 Data Register	PDR4	R/W	Port 4	$XXXXXXXX_B$
000005_H	Port 5 Data Register	PDR5	R/W	Port 5	$XXXXXXXX_B$
000006_H	Port 6 Data Register	PDR6	R/W	Port 6	$XXXXXXXX_B$
000007_H to $00000A_H$	Reserved				
$00000B_H$	Port 5 Analog Input Enable Register	ADER5	R/W	Port 5, A/D	11111111_B
$00000C_H$	Port 6 Analog Input Enable Register	ADER6	R/W	Port 6, A/D	11111111_B
$00000D_H$	Reserved				
$00000E_H$	Input Level Select Register 0	ILSR0	R/W	Ports	00000000_B
$00000F_H$	Input Level Select Register 1	ILSR1	R/W	Ports	00000000_B
000010_H	Port 0 Direction Register	DDR0	R/W	Port 0	00000000_B
000011_H	Port 1 Direction Register	DDR1	R/W	Port 1	00000000_B
000012_H	Port 2 Direction Register	DDR2	R/W	Port 2	$XX000000_B$
000013_H	Port 3 Direction Register	DDR3	R/W	Port 3	00000000_B
000014_H	Port 4 Direction Register	DDR4	R/W	Port 4	$XX000000_B$
000015_H	Port 5 Direction Register	DDR5	R/W	Port 5	$X0000000_B$
000016_H	Port 6 Direction Register	DDR6	R/W	Port 6	00000000_B
000017_H to 000019_H	Reserved				
$00001A_H$	SIN input Level Setting Register	DDRA	W	UART2, UART3	$X00XXXXX_B$
$00001B_H$	Reserved				
$00001C_H$	Port 0 Pull-up Control Register	PUCR0	R/W	Port 0	00000000_B
$00001D_H$	Port 1 Pull-up Control Register	PUCR1	R/W	Port 1	00000000_B
$00001E_H$	Port 2 Pull-up Control Register	PUCR2	R/W	Port 2	00000000_B
$00001F_H$	Port 3 Pull-up Control Register	PUCR3	R/W	Port 3	00000000_B
000020_H to 000037_H	Reserved				

(Continued)

Address	Register	Abbreviation	Access	Resource name	Initial value
000058_H to $00005B_H$	Reserved				
$00005C_H$	Output Compare Control Status Register 4	OCS4	R/W	Output Compare 4/5	$0000XX00_B$
$00005D_H$	Output Compare Control Status Register 5	OCS5	R/W		$0XX00000_B$
$00005E_H$	Output Compare Control Status Register 6	OCS6	R/W	Output Compare 6/7	$0000XX00_B$
$00005F_H$	Output Compare Control Status Register 7	OCS7	R/W		$0XX00000_B$
000060_H	Timer Control Status Register 0	TMCSR0	R/W	16-bit Reload Timer 0	00000000_B
000061_H	Timer Control Status Register 0	TMCSR0	R/W		$XXXX0000_B$
000062_H	Timer Control Status Register 1	TMCSR1	R/W	16-bit Reload Timer 1	00000000_B
000063_H	Timer Control Status Register 1	TMCSR1	R/W		$XXXX0000_B$
000064_H	Timer Control Status Register 2	TMCSR2	R/W	16-bit Reload Timer 2	00000000_B
000065_H	Timer Control Status Register 2	TMCSR2	R/W		$XXXX0000_B$
000066_H	Timer Control Status Register 3	TMCSR3	R/W	16-bit Reload Timer 3	00000000_B
000067_H	Timer Control Status Register 3	TMCSR3	R/W		$XXXX0000_B$
000068_H	A/D Control Status Register 0	ADCS0	R/W	A/D Converter	$000XXXX0_B$
000069_H	A/D Control Status Register 1	ADCS1	R/W		$0000000X_B$
$00006A_H$	A/D Data Register 0	ADCR0	R		00000000_B
$00006B_H$	A/D Data Register 1	ADCR1	R		$XXXXXX00_B$
$00006C_H$	ADC Setting Register 0	ADSR0	R/W		00000000_B
$00006D_H$	ADC Setting Register 1	ADSR1	R/W		00000000_B
$00006E_H$	Low Voltage/CPU Operation Detection Reset Control Register	LVRC	R/W, W	Low Voltage/CPU Operation Detection Reset	00111000_B
$00006F_H$	ROM Mirror Function Select Register	ROMM	W	ROM Mirror	$XXXXXXX1_B$
000070_H to $00007F_H$	Reserved				
000080_H to $00008F_H$	Reserved for CAN controller 1. Refer to “CAN Controllers”				
000090_H to $00009A_H$	Reserved				

(Continued)

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(T_A = −40°C to +125°C, V_{CC} = 5.0 V ± 10%, f_{CP} ≤ 24 MHz, V_{SS} = AV_{SS} = 0 V)

Parameter	Symbol	Pin	Condition	Value			Unit	Remarks
				Min	Typ	Max		
Power supply current	I_{CCT}	V_{CC}	V_{CC} = 5.0 V, Internal frequency: 8 kHz, During stopping clock supervisor, At watch mode T_A = +25°C	—	10	35	µA	MB90351E MB90F351E MB90352E MB90F352E MB90356E MB90F356E MB90357E MB90F357E
			V_{CC} = 5.0 V, Internal frequency: 8 kHz, During operating clock supervisor, At watch mode T_A = +25°C	—	25	150	µA	MB90356E MB90F356E MB90357E MB90F357E
			V_{CC} = 5.0 V, Internal CR oscillation/ 4 division, At watch mode T_A = +25°C	—	25	150	µA	MB90356ES MB90F356ES MB90357ES MB90F357ES
			V_{CC} = 5.0 V, Internal frequency: 8 kHz, During stopping clock supervisor, At watch mode T_A = +25°C	—	60	140	µA	MB90351TE MB90F351TE MB90352TE MB90F352TE MB90356TE MB90F356TE MB90357TE MB90F357TE
			V_{CC} = 5.0 V, Internal frequency: 8 kHz, During operating clock supervisor, At watch mode T_A = +25°C	—	80	250	µA	MB90356TE MB90F356TE MB90357TE MB90F357TE
			V_{CC} = 5.0 V, Internal CR oscillation/ 4 division, At watch mode T_A = +25°C	—	80	250	µA	MB90356TES MB90F356TES MB90357TES MB90F357TES
	I_{CCH}		V_{CC} = 5.0 V, At stop mode, T_A = +25°C	—	7	25	µA	Devices without “T”-suffix
				—	60	130	µA	Devices with “T”-suffix
Input capacity	C_{IN}	Other than C, AV_{CC}, AV_{SS}, AVRH, V_{CC}, V_{SS}	—	—	5	15	pF	

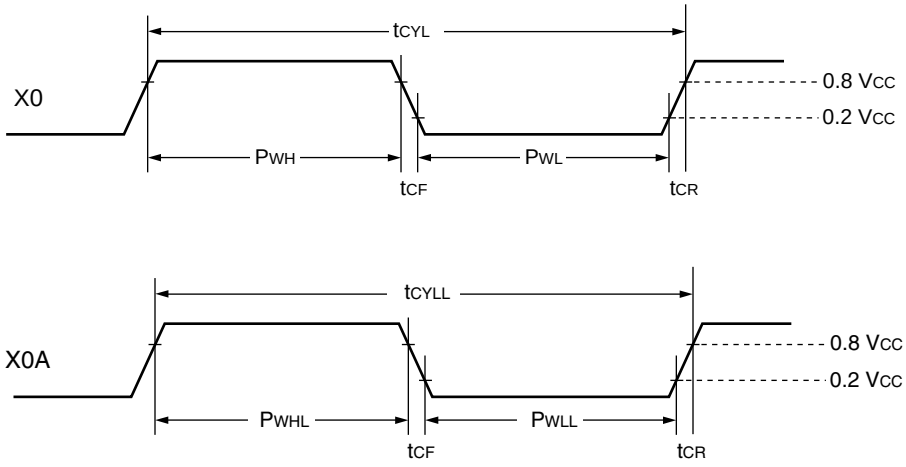
(Continued)

(T_A = –40°C to +125°C, V_{CC} = 5.0 V ± 10%, f_{CP} ≤ 24 MHz, V_{SS} = AV_{SS} = 0 V)

Parameter	Symbol	Pin	Value			Unit	Remarks
			Min	Typ	Max		
Internal operating clock frequency (machine clock)	f_{CP}	—	1.5	—	24	MHz	When using main clock
	f_{CPL}	—	—	8.192	50	kHz	When using sub clock
Internal operating clock cycle time (machine clock)	t_{CP}	—	41.67	—	666	ns	When using main clock
	t_{CPL}	—	20	122.1	—	µs	When using sub clock

*: The limitation is in the range of the clock frequency when PLL is used. Use within the range in graph of "· PLL guaranteed operation range External clock frequency and internal operation clock frequency".

- Clock Timing

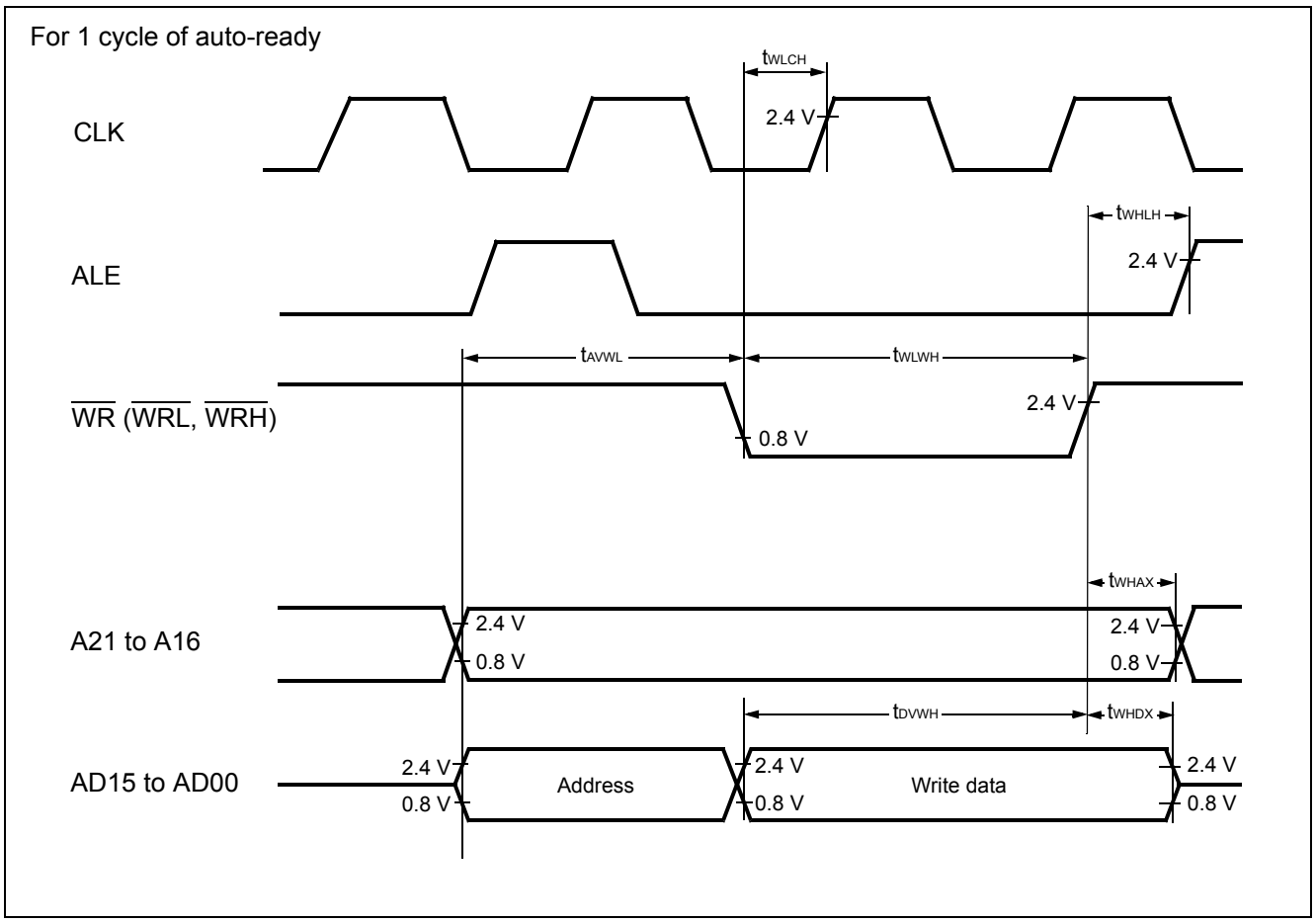


13.4.6 Bus Timing (Write)

(T_A = –40°C to +105°C, V_{CC} = 5.0 V ± 10 %, V_{SS} = 0.0 V, f_{CP} ≤ 24 MHz)

Parameter	Symbol	Pin	Condition	Value		Unit
				Min	Max	
Valid address → $\overline{WR}$ ↓ time	t_{AVWL}	A21 to A16, AD15 to AD00, $\overline{WR}$	–	t_{CP}–15	–	ns
$\overline{WR}$ pulse width	t_{WLWH}	$\overline{WR}$		(n*+3/2)t_{CP} – 20	–	ns
Valid data output → $\overline{WR}$ ↑ time	t_{DVWH}	AD15 to AD00, $\overline{WR}$		(n*+3/2)t_{CP} – 20	–	ns
$\overline{WR}$ ↑ → Data hold time	t_{WHDX}	AD15 to AD00, $\overline{WR}$		15	–	ns
$\overline{WR}$ ↑ → Address valid time	t_{WHAX}	A21 to A16, $\overline{WR}$		t_{CP}/2 – 10	–	ns
$\overline{WR}$ ↑ → ALE ↑ time	t_{WHLH}	$\overline{WR}$, ALE		t_{CP}/2 – 15	–	ns
$\overline{WR}$ ↓ → CLK ↑ time	t_{WLCH}	$\overline{WR}$, CLK		t_{CP}/2 – 15	–	ns

* : Number of ready cycles

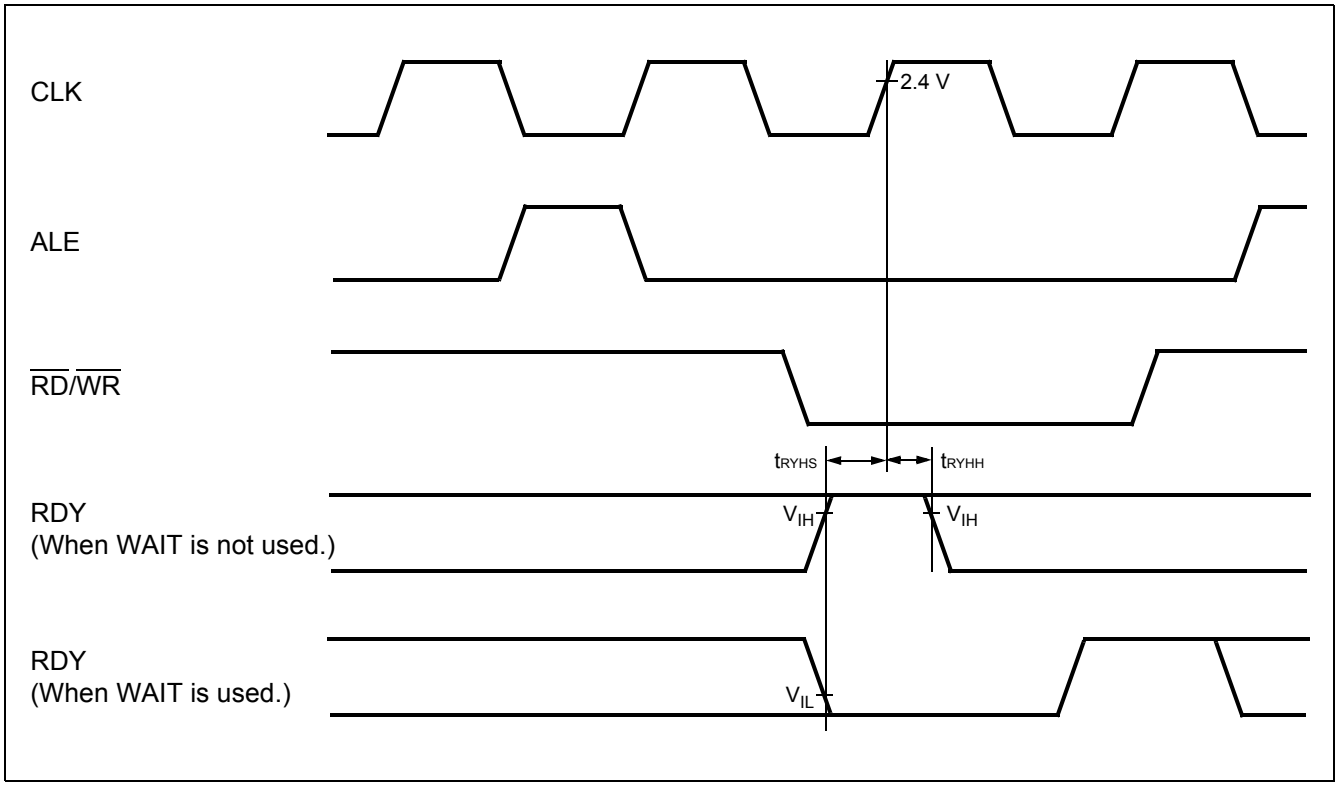


13.4.7 Ready Input Timing

(T_A = –40°C to +105°C, V_{CC} = 5.0 V ± 10 %, V_{SS} = 0.0 V, f_{CP} ≤ 24 MHz)

Parameter	Symbol	Pin	Condition	Value		Units	Remarks
				Min	Max		
RDY set-up time	t_{RYHS}	RDY	—	45	—	ns	f_{CP} = 16 MHz
				32	—	ns	f_{CP} = 24 MHz
RDY hold time	t_{RYHH}	RDY		0	—	ns	

Note : If the RDY set-up time is insufficient, use the auto-ready function.



13.4.9 LIN-UART2/3

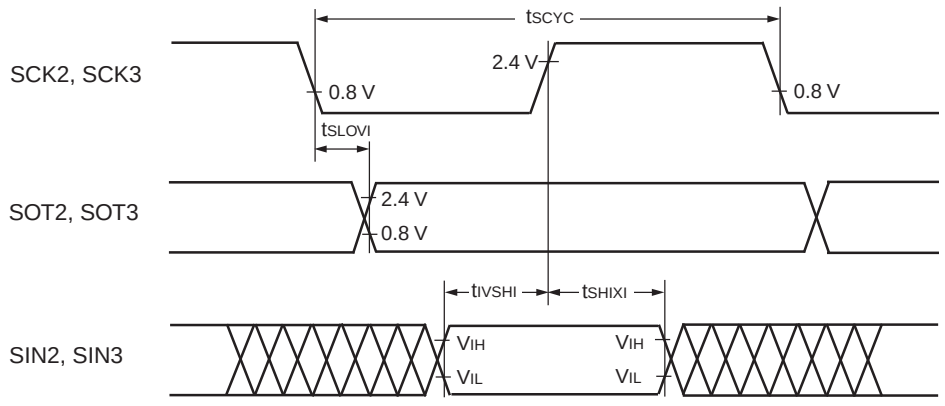
■ Bit setting: ESCR:SCES = 0, ECCR:SCDE = 0

(T_A = –40°C to +125°C, V_{CC} = 5.0 V ± 10%, f_{CP} ≤ 24 MHz, V_{SS} = 0 V)

Parameter	Symbol	Pin	Condition	Value		Unit
				Min	Max	
Serial clock cycle time	t_{SCYC}	SCK2, SCK3	Internal shift clock mode output pins are CL = 80 pF + 1 TTL.	5 t_{CP}	—	ns
SCK ↓ → SOT delay time	t_{SLOVI}	SCK2, SCK3 SOT2, SOT3		–50	+50	ns
Valid SIN → SCK ↑	t_{IVSHI}	SCK2, SCK3 SIN2, SIN3		t_{CP} + 80	—	ns
SCK ↑ → Valid SIN hold time	t_{SHIXI}	SCK2, SCK3 SIN2, SIN3		0	—	ns
Serial clock “L” pulse width	t_{SHSL}	SCK2, SCK3	External shift clock mode output pins are CL = 80 pF + 1 TTL.	3 t_{CP} - t_R	—	ns
Serial clock “H” pulse width	t_{SLSH}	SCK2, SCK3		t_{CP} + 10	—	ns
SCK ↓ → SOT delay time	t_{SLOVE}	SCK2, SCK3 SOT2, SOT3		—	2 t_{CP} + 60	ns
Valid SIN → SCK ↑	t_{IVSHE}	SCK2, SCK3 SIN2, SIN3		30	—	ns
SCK ↑ → Valid SIN hold time	t_{SHIXE}	SCK2, SCK3 SIN2, SIN3		t_{CP} + 30	—	ns
SCK fall time	t_F	SCK2, SCK3		—	10	ns
SCK rise time	t_R	SCK2, SCK3		—	10	ns

Notes :
- AC characteristic in CLK synchronized mode.
- C_L is load capacity value of pins when testing.
- t_{CP} is internal operating clock cycle time (machine clock) . Refer to “Clock Timing”.

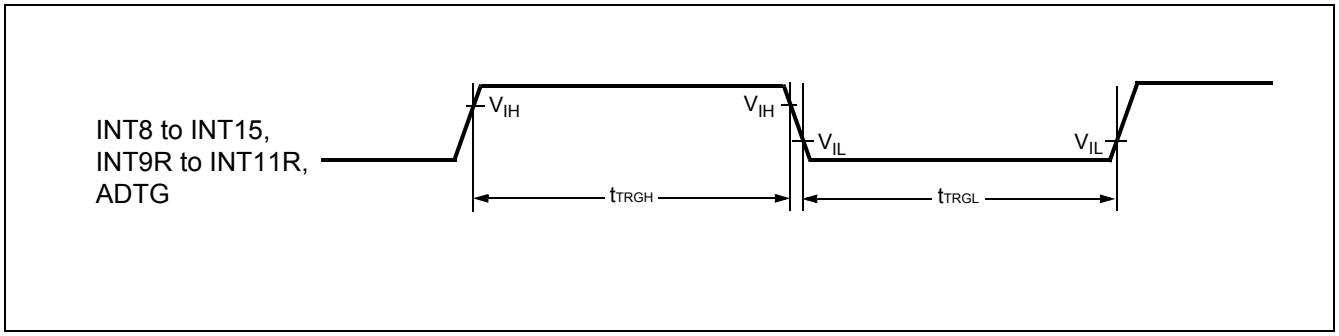
″ Internal Shift Clock Mode



13.4.10 Trigger Input Timing

(T_A = –40°C to +125°C, V_{CC} = 5.0 V ± 10%, f_{CP} ≤ 24 MHz, V_{SS} = AV_{SS} = 0 V)

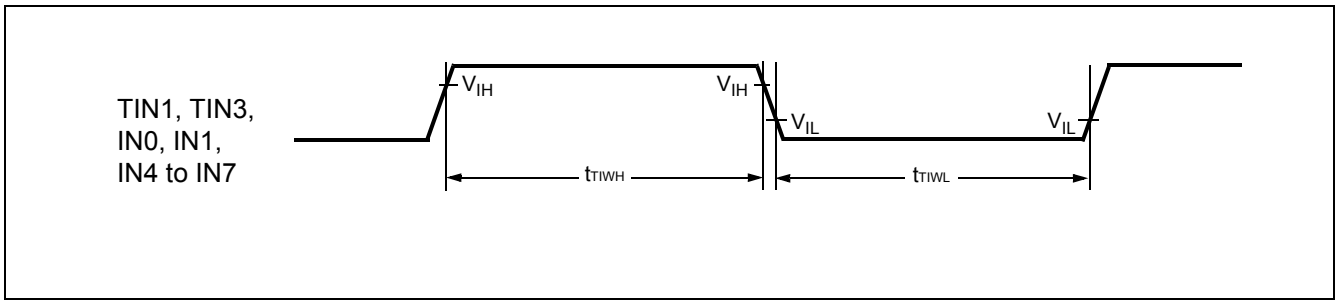
Parameter	Symbol	Pin	Condition	Value		Unit
				Min	Max	
Input pulse width	t_{TRGH} t_{TRGL}	INT8 to INT15, INT9R to INT11R, ADTG	—	5 t_{CP}	—	ns



13.4.11 Timer Related Resource Input Timing

(T_A = –40°C to +125°C, V_{CC} = 5.0 V ± 10%, f_{CP} ≤ 24 MHz, V_{SS} = AV_{SS} = 0 V)

Parameter	Symbol	Pin	Condition	Value		Unit
				Min	Max	
Input pulse width	t_{TIWH} t_{TIWL}	TIN1, TIN3,IN0, IN1, IN4 to IN7	—	4 t_{CP}	—	ns

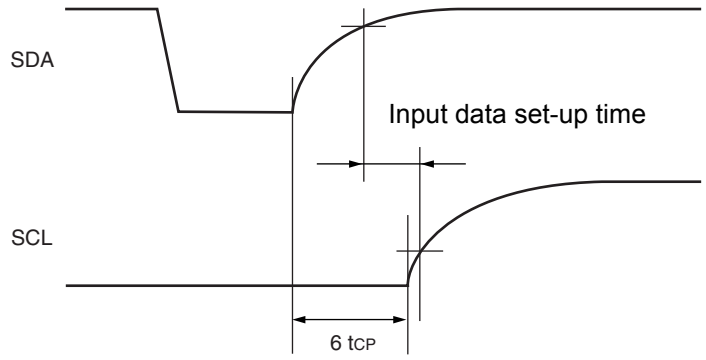


13.4.12 Timer Related Resource Output Timing

(T_A = –40°C to +125°C, V_{CC} = 5.0 V ± 10%, f_{CP} ≤ 24 MHz, V_{SS} = AV_{SS} = 0 V)

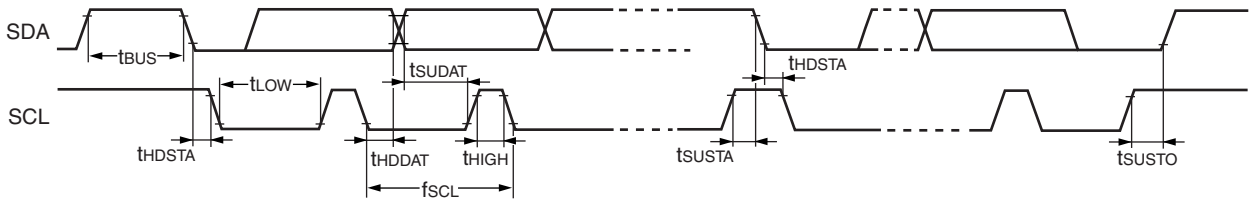
Parameter	Symbol	Pin	Condition	Value		Unit
				Min	Max	
CLK ↑ → T_{OUT} change time	t_{TO}	TOT1, TOT3, PPG4, PPG6, PPG8 to PPGF	—	30	—	ns

• Note of SDA, SCL set-up time



Note : The rating of the input data set-up time in the device connected to the bus cannot be satisfied depending on the load capacitance or pull-up resistor.
Be sure to adjust the pull-up resistor of SDA and SCL if the rating of the input data set-up time cannot be satisfied.

• Timing definition



13.5 A/D Converter

(T_A = −40°C to +125°C, 3.0 V ≤ AVRH, V_{CC} = AV_{CC} = 5.0 V ± 10%, f_{CP} ≤ 24 MHz, V_{SS} = AV_{SS} = 0 V)

Parameter	Symbol	Pin	Value			Unit	Remarks
			Min	Typ	Max		
Resolution	—	—	—	—	10	bit	
Total error	—	—	—	—	±3.0	LSB	
Nonlinearity error	—	—	—	—	±2.5	LSB	
Differential nonlinearity error	—	—	—	—	±1.9	LSB	
Zero reading voltage	V_{OT}	AN0 to AN14	AV_{SS} − 1.5×LSB	AV_{SS} + 0.5×LSB	AV_{SS} + 2.5×LSB	V	
Full scale reading voltage	V_{FST}	AN0 to AN14	AVRH − 3.5×LSB	AVRH − 1.5×LSB	AVRH + 0.5×LSB	V	
Compare time	—	—	1.0	—	16500	µs	4.5 V ≤ AV_{CC} ≤ 5.5 V
			2.0				4.0 V ≤ AV_{CC} < 4.5 V
Sampling time	—	—	0.5	—	×	µs	4.5 V ≤ AV_{CC} ≤ 5.5 V
			1.2				4.0 V ≤ AV_{CC} < 4.5 V
Analog port input current	I_{AIN}	AN0 to AN14	− 0.3	—	+ 0.3	µA	
Analog input voltage range	V_{AIN}	AN0 to AN14	AV_{SS}	—	AVRH	V	
Reference voltage range	—	AVRH	AV_{SS} + 2.7	—	AV_{CC}	V	
Power supply current	I_A	AV_{CC}	—	3.5	7.5	mA	
	I_{AH}	AV_{CC}	—	—	5	µA	*
Reference voltage supply current	I_R	AVRH	—	600	900	µA	
	I_{RH}	AVRH	—	—	5	µA	*
Offset between channels	—	AN0 to AN14	—	—	4	LSB	

* : If A/D converter is not operating, a current when CPU is stopped is applicable (V_{CC} = AV_{CC} = AVRH = 5.0 V) .

Notes on A/D Converter Section

■ About the external impedance of the analog input and its sampling time

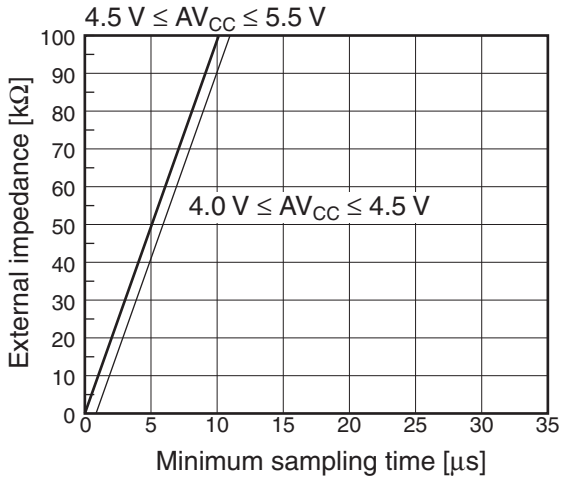
A/D converter with sample and hold circuit. If the external impedance is too high to keep sufficient sampling time, the analog voltage charged to the internal sample and hold capacitor is insufficient, adversely affecting
A/D conversion precision. Therefore to satisfy the A/D conversion precision standard, consider the relationship between the external impedance and minimum sampling time and either adjust the register value and operating frequency or decrease the external impedance so that the sampling time is longer than the minimum value. Also if the sampling time cannot be sufficient, connect a capacitor of about 0.1 µF to the analog input pin.

■ MASK ROM device

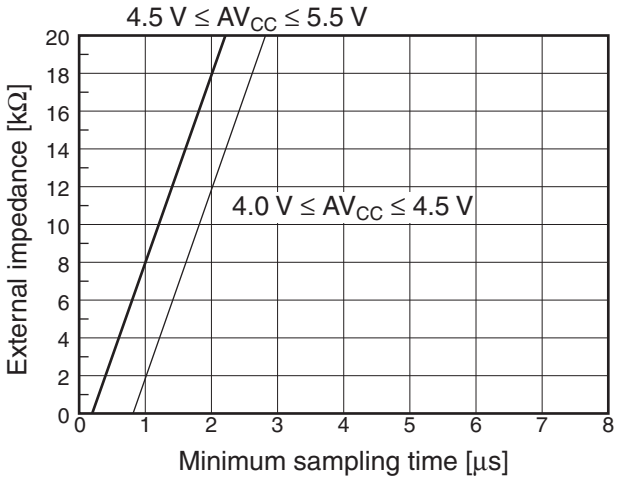
· Relation between External impedance and minimum sampling time

(MB90351E(S),MB90351TE(S),MB90352E(S),MB90352TE(S),MB90356E(S), MB90356TE(S),MB90357E(S),MB90357TE(S),MB90V340E-101/102/103/104)

[External impedance = 0 kΩ to 100 kΩ]



[External impedance = 0 kΩ to 20kΩ]

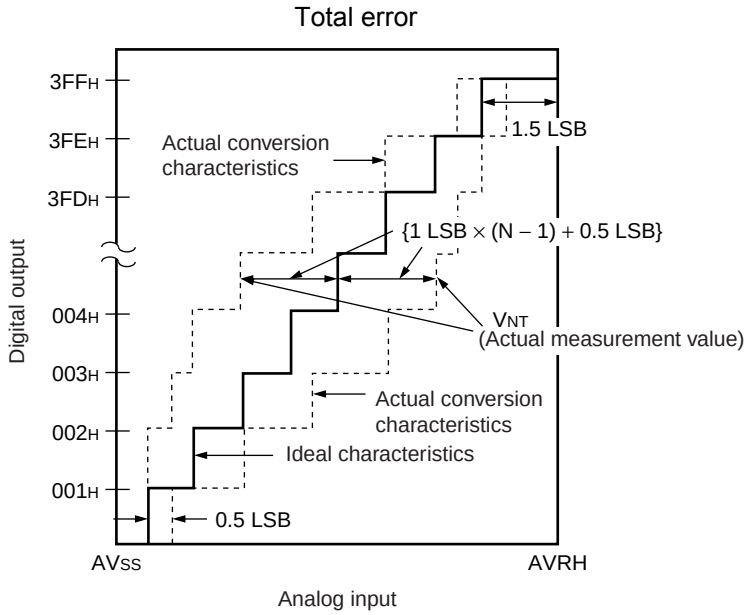


■ About the error

Values of relative errors grow larger, as |AVRH − AV_{SS}| becomes smaller.

13.6 Definition of A/D Converter Terms

Resolution	:	Analog variation that is recognized by an A/D converter.
Non linearity error	:	Deviation between a line across zero-transition line (“00 0000 0000” ← → “00 0000 0001”) and full-scale transition line (“11 1111 1110” ← → “11 1111 1111”) and actual conversion characteristics.
Differential linearity error	:	Deviation of input voltage, which is required for changing output code by 1 LSB, from an ideal value.
Total error	:	Difference between an actual value and a theoretical value. A total error includes zero transition error, full-scale transition error, and linear error.



$$\text{Total error of digital output “N”} = \frac{V_{NT} - \{1\ \text{LSB} \times (N - 1) + 0.5\ \text{LSB}\}}{1\ \text{LSB}}\ [\text{LSB}]$$

$$1\ \text{LSB (Ideal value)} = \frac{AVRH - AV_{SS}}{1024}\ [\text{V}]$$

N : A/D converter digital output value

V_{OT} (Ideal value) $= AV_{SS} + 0.5$ LSB [V]

V_{FST} (Ideal value) $= AVRH - 1.5$ LSB [V]

V_{NT} : A voltage at which digital output transits from $(N - 1)_H$ to N_H.

(Continued)

Parameter	Conditions	Value			Unit	Remarks
		Min	Typ	Max		
Flash memory Data Retention Time	Average T_A = +85°C	20	—	—	year	*

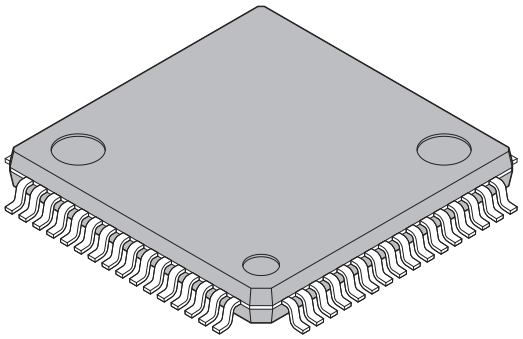
* : Corresponding value comes from the technology reliability evaluation result.
(Using Arrhenius equation to translate high temperature measurements test result into normalized value at +85°C)

14. Ordering Information

Part number	Package	Remarks
MB90F351EPMC	64-pin plastic LQFP FPT-64P-M23 12.0 mm □, 0.65 mm pitch	Flash memory products (64 Kbytes)
MB90F351ESPMC		
MB90F351TEPMC		
MB90F351TESPMC		
MB90F356EPMC		
MB90F356ESPMC		
MB90F356TEPMC		
MB90F356TESPMC		
MB90F352EPMC	64-pin plastic LQFP FPT-64P-M23 12.0 mm □, 0.65 mm pitch	Dual operation Flash memory products (128 Kbytes)
MB90F352ESPMC		
MB90F352TEPMC		
MB90F352TESPMC		
MB90F357EPMC		
MB90F357ESPMC		
MB90F357TEPMC		
MB90F357TESPMC		
MB90351EPMC	64-pin plastic LQFP FPT-64P-M23 12.0 mm □, 0.65 mm pitch	MASK ROM products (64 Kbytes)
MB90351ESPMC		
MB90351TEPMC		
MB90351TESPMC		
MB90356EPMC		
MB90356ESPMC		
MB90356TEPMC		
MB90356TESPMC		
MB90352EPMC	64-pin plastic LQFP FPT-64P-M23 12.0 mm □, 0.65 mm pitch	MASK ROM products (128 Kbytes)
MB90352ESPMC		
MB90352TEPMC		
MB90352TESPMC		
MB90357EPMC		
MB90357ESPMC		
MB90357TEPMC		
MB90357TESPMC		

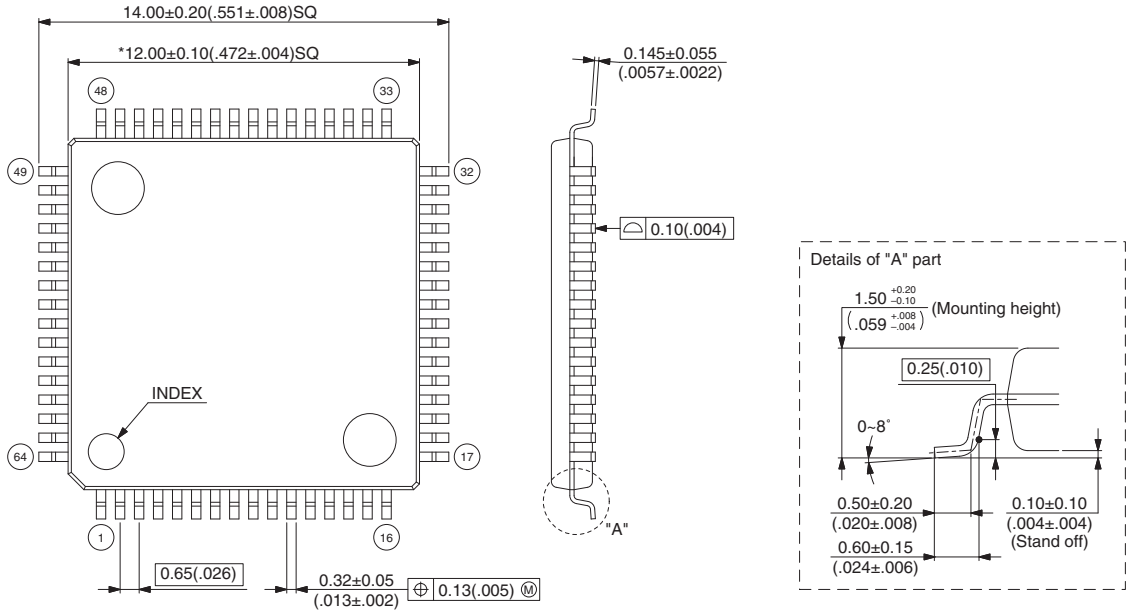
(Continued)

14.1 Package Dimensions

64-pin plastic LQFP		
	Lead pitch	0.65 mm
	Package width × package length	12.0 × 12.0 mm
	Lead shape	Gullwing
	Sealing method	Plastic mold
	Mounting height	1.70 mm MAX
	Code (Reference)	P-LFQFP64-12×12-0.65
(FPT-64P-M23)		

64-pin plastic LQFP
(FPT-64P-M23)

Note 1) * : These dimensions do not include resin protrusion.
Note 2) Pins width and pins thickness include plating thickness.
Note 3) Pins width do not include tie bar cutting remainder.



Dimensions in mm (inches).
Note: The values in parentheses are reference values

(Continued)